

FPGA Configuration Flash Memory

DATASHEET

Features

- Programmable 16,777,216 x 1-bit Serial Memories Designed to Store Configuration Programs for Field Programmable Gate Arrays (FPGAs)
- 3.3V Output Capability
- 5.0V Tolerant I/O Pins
- Program Support using the Atmel ATDH2200E System, ATDH2225 ISP Cable, or Third-party Programmers
- In-System Programmable (ISP) via 2-wire Bus
- Simple Interface to SRAM FPGAs
- Compatible with Atmel AT40K and AT94K Devices, Altera[®] FLEX[®], APEX[™] Devices, Lucent[®] ORCA[®] FPGAs, Xilinx[®] XC3000, XC4000, XC5200, Spartan[®], Virtex[®] FPGAs, Motorola[®] MPA1000 FPGAs
- Cascadable Read-back to Support Additional Configurations or Higher-density Arrays
- Low-power CMOS FLASH Process
- Available in 8-pad LAP (Pin-compatible with 8-lead SOIC/VOIC Footprint Packages) and 20-lead PLCC Packages
- Emulation of the Atmel AT24C Serial EEPROMs
- Low-power Standby Mode
- Single Device Capable of Holding Four Bitstream Files Allowing Simple System Reconfiguration
- Fast Serial Download Speeds up to 33MHz
- Endurance: 10,000 Write Cycles Typical
- Green (Pb/Halide-free/RoHS Compliant) Packages

Description

The Atmel® AT17F16 In-System Programmable Configuration PROMs (Configurators) provide an easy-to-use, cost-effective configuration memory solutions for FPGAs. The AT17F16 is packaged in the 8-pad LAP and 20-lead PLCC packages (Table 1). The AT17F16 uses a simple serial-access procedure to configure one or more FPGA devices.

The AT17F16 can be programmed with industry-standard programmers, the Atmel ATDH2200E Programming Kit, or the Atmel ATDH2225 ISP Cable.

Table 1. AT17F16 Packages

| Package | AT17F16 |
|--------------|---------|
| 8-pad LAP | Yes |
| 20-lead PLCC | Yes |

1. Pin Configurations

Table 1-1. Pin Descriptions

| configuration programming. Clock Input. Used to increment programming. Enable Page Download Mode Input. Space is partitioned into four equal put multiple configuration bitstreams frow with the PAGESEL inputs. PAGE_E Low (ISP mode) this pin has no effect of the page Select Inputs. Used to determ configuration download. The address SER_EN is Low (ISP mode) these pages. | mine which of the four memory pages are targeted during a serial as space for each of the pages is shown in Table 1-2. When |
|---|---|
| PAGESEL[1:0] ⁽²⁾ PAGESEL[1:0] ⁽²⁾ programming. Enable Page Download Mode Inp space is partitioned into four equal pmultiple configuration bitstreams frow with the PAGESEL inputs. PAGE_E Low (ISP mode) this pin has no effect of the page Select Inputs. Used to determ configuration download. The address SER_EN is Low (ISP mode) these pages. | ut. When PAGE_EN is high, the configuration download address pages. This gives users the ability to easily store and retrieve om a single configuration device. This input works in conjunction EN must be remain low if paging is not desired. When SER_EN is act. The page is a special desired and the pages are targeted during a serial as space for each of the pages is shown in Table 1-2. When poins have no effect. RESET (Active Low) when SER_EN is High. A Low level on |
| space is partitioned into four equal pmultiple configuration bitstreams frow with the PAGESEL inputs. PAGE_E Low (ISP mode) this pin has no effect of the page Select Inputs. Used to determ configuration download. The address SER_EN is Low (ISP mode) these page Select Inputs. | pages. This gives users the ability to easily store and retrieve on a single configuration device. This input works in conjunction EN must be remain low if paging is not desired. When SER_EN is ect. This input works in conjunction is not desired. When SER_EN is ect. This input works in conjunction is not desired. When SER_EN is ect. This input works in conjunction in the series is not desired. When series is space for each of the pages is shown in Table 1-2. When bins have no effect. The input works in conjunction in the series is series in the series |
| PAGESEL[1:0] ⁽²⁾ configuration download. The address SER_EN is Low (ISP mode) these page 1. | ss space for each of the pages is shown in Table 1-2. When bins have no effect. RESET (Active Low) when SER_EN is High. A Low level on |
| | |
| | - , |
| CE ⁽¹⁾ counter and enables the data output counters and forces the device into | A Low level (with OE High) allows CLK to increment the address t driver. A High level on $\overline{\text{CE}}$ disables both the address and bit a low-power standby mode. Note that this pin will <i>not vi</i> re Serial Programming mode ($\overline{\text{SER}}$ _EN Low). |
| GND Ground . A 0.2µF decoupling capac | itor between V _{CC} and GND is recommended. |
| counter has reached its maximum v highest address in the selected part partition selections. If the PAGE_EN maximum value is the highest addre devices, the CEO pin of one device | EN is High). This output goes Low when the internal address alue. If the PAGE_EN input is set High, the maximum value is the tition. The PAGESEL[1:0] inputs are used to make the four N input is set Low, the device is not partitioned and the address less in the device (Table 1-2). In a daisy chain of AT17F Series must be connected to the $\overline{\text{CE}}$ input of the next device in the chain. It will then follow $\overline{\text{CE}}$ until OE goes Low; the entire EEPROM is read again. |
| | R_EN Low). The input is used to enable (or chip select) the nen SER_EN is Low). Refer to the AT17F(A) Programming el.com for additional details. |
| READY Open Collector Reset State Indica is complete. (Recommend 4.7kΩ pu | ator. Driven Low during power-up reset, released when power-up ull-up on this pin if used). |
| | High during FPGA configuration operations. Bringing SER_EN ramming Mode. For non-ISP applications, SER_EN should be |
| V _{CC} Device Power Supply. +3.3V (±10) | %) |

Notes: 1. Internal $20K\Omega$ pull-up resistor

2. Internal $30K\Omega$ pull-up resistor

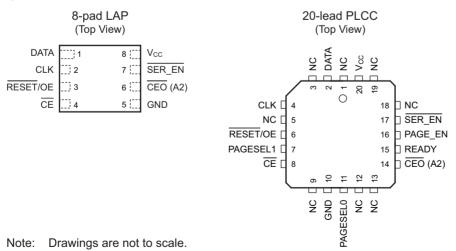
Table 1-2. Address Space PAGESEL[1:0]

| Paging Decodes | AT17F16 (16Mb) |
|---------------------------|----------------|
| PAGESEL = 00, PAGE_EN = 1 | 00000 – 3FFFFh |
| PAGESEL = 01, PAGE_EN = 1 | 40000 – 7FFFFh |
| PAGESEL = 10, PAGE_EN = 1 | 80000 – BFFFFh |
| PAGESEL = 11, PAGE_EN = 1 | C0000 – FFFFFh |
| PAGESEL = XX, PAGE_EN = 0 | 00000 – FFFFFh |

Table 1-3. Pin Configurations

| Name | I/O | 8-pad LAP | 20-lead PLCC |
|-----------------|-----|-----------|--------------|
| DATA | I/O | 1 | 2 |
| CLK | I | 2 | 4 |
| PAGE_EN | I | _ | 16 |
| PAGESEL0 | I | _ | 11 |
| PAGESEL1 | I | _ | 7 |
| RESET/OE | 1 | 3 | 6 |
| CE | I | 4 | 8 |
| GND | _ | 5 | 10 |
| CEO | 0 | 6 | 14 |
| A2 | I | 6 | 14 |
| READY | 0 | _ | 15 |
| SER_EN | I | 7 | 17 |
| V _{CC} | _ | 8 | 20 |

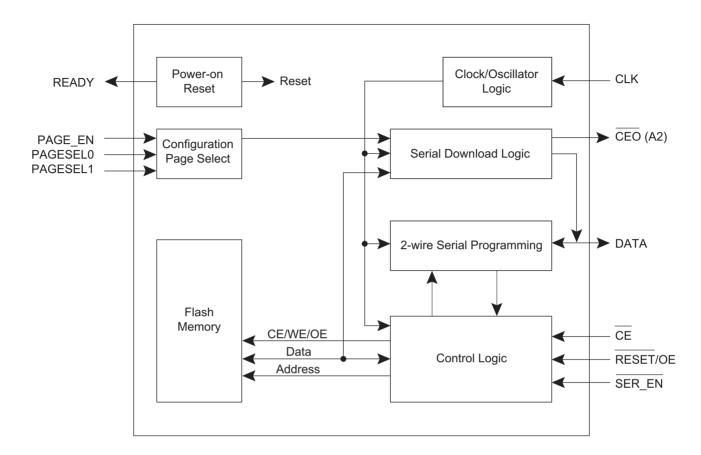
Figure 1-1. **Pinouts**





2. Block Diagram

Figure 2-1. Block Diagram



3. Device Description

The control signals for the configuration memory device (\overline{CE} , \overline{RESET}/OE and CLK) interface directly with the FPGA device control signals. All FPGA devices can control the entire configuration process and retrieve data from the configuration device without requiring an external intelligent controller.

The $\overline{\text{RESET}}/\text{OE}$ and $\overline{\text{CE}}$ pins control the tri-state buffer on the DATA output pin and enable the address counter. When $\overline{\text{RESET}}/\text{OE}$ is driven Low, the configuration device resets its address counter and tri-states its DATA pin. The $\overline{\text{CE}}$ pin also controls the output of the AT17F16. If $\overline{\text{CE}}$ is held High after the $\overline{\text{RESET}}/\text{OE}$ reset pulse, the counter is disabled and the DATA output pin is tri-stated. When OE is subsequently driven High, the counter and the DATA output pin are enabled. When $\overline{\text{RESET}}/\text{OE}$ is driven Low again, the address counter is reset and the DATA output pin is tri-stated, regardless of the state of $\overline{\text{CE}}$.

When the configurator has driven out all of its data and $\overline{\text{CEO}}$ is driven Low, the device tri-states the DATA pin to avoid contention with other configurators. Upon power-up, the address counter is automatically reset.

4. FPGA Master Serial Mode Summary

The I/O and logic functions of any SRAM-based FPGA are established by a configuration program. The program is loaded either automatically upon power-up, or on command, depending on the state of the FPGA mode pins. In Master mode, the FPGA automatically loads the configuration program from an external memory. The AT17F16 Serial Configuration PROM has been designed for compatibility with the Master Serial mode.

This document discusses the Atmel AT40K, AT40KAL and AT94KAL applications as well as Xilinx applications.

5. Control of Configuration

Most connections between the FPGA device and the AT17F16 Serial Configurator PROM are simple and self-explanatory.

- The DATA output of the AT17F16 Configurator drives DIN of the FPGA devices.
- The master FPGA CCLK output drives the CLK input of the AT17F16 Configurator.
- The $\overline{\text{CEO}}$ output of any AT17F16 Configurator drives the $\overline{\text{CE}}$ input of the next Configurator in a cascade chain of configurator devices.
- SER_EN must be connected to V_{CC} or allowed to float to logic High via the internal pull-up resistor (except during ISP).
- The READY pin is available as an open-collector indicator of the device's reset status; it is driven Low while the device is in its power-on reset cycle and released (tri-stated) when the cycle is complete.
- PAGE_EN must be held Low if download paging is not desired. The PAGESEL[1:0] inputs must be tied off
 High or Low. If paging is desired, PAGE_EN must be High and the PAGESEL pins must be set to High or
 Low such that the desired page is selected, see Table 1-2.

6. Cascading Serial Configuration Devices

For multiple FPGAs configured as a daisy-chain, or for FPGAs requiring larger configuration memories, cascaded configurators provide additional memory.

After the last bit from the first configurator is read, the clock signal to the configurator asserts its $\overline{\text{CEO}}$ output Low and disables its DATA line driver. The second configurator recognizes the Low level on its $\overline{\text{CE}}$ input and enables its DATA output.

After configuration is complete, the address counters of all cascaded configurators are reset if the RESET/OE on each configurator is driven to its active (Low) level.

If the address counters are not to be reset upon completion, then the $\overline{\text{RESET}}/\text{OE}$ input can be tied to its inactive (High) level.



7. Programming Mode

The programming mode is entered by bringing $\overline{SER_EN}$ Low. In this mode the chip can be programmed by the 2-wire serial bus. The programming is done at V_{CC} supply only. Programming super voltages are generated inside the chip. The AT17F16 is read/write at 3.3V nominal. Refer to the AT17F16(A) Programming Specification available on www.atmel.com for more programming details. The AT17F16 is supported by the Atmel ATDH2200E programming system along with many third party programmers.

8. Standby Mode

The AT17F16 enters a low-power standby mode whenever $\overline{\text{SER_EN}}$ is High and $\overline{\text{CE}}$ is asserted High. In this mode, the AT17F16 consumes less than 2mA of current at 3.6V. The output remains in a high-impedance state regardless of the state of the OE input.

9. Electrical Specifications

9.1 Absolute Maximum Ratings*

| Operating ⁻ | Temperature40°C to +85°C |
|------------------------|--|
| Storage Te | emperature65°C to +150°C |
| Voltage on with Respe | Any Pin ect to Ground |
| Supply Vol | tage (V _{CC})0.5V to +4.0V |
| Maximum S | Soldering Temp. (10 sec. @ 1/16in.)260°C |
| ESD (R _{ZAP} | = 1.5K, C _{ZAP} = 100pF) 2000V |

*Notice: Stresses beyond those listed under
Absolute Maximum Ratings may cause
permanent damage to the device. This is
a stress rating only and functional
operation of the device at these or any
other conditions beyond those listed
under operating conditions is not implied.
Exposure to Absolute Maximum Rating
conditions for extended periods of time
may affect device reliability.

9.2 Operating Conditions

Table 9-1. Operating Conditions

| Symbol | Description | Min | Max | Units |
|-----------------|---|------|------|-------|
| V _{CC} | Supply voltage relative to GND -40°C to +85°C | 2.97 | 3.63 | V |

9.3 DC Characteristics

Table 9-2. DC Characteristics

| Symbol | Description | Min | Max | Units |
|------------------|--|-----|-----------------|-------|
| V _{IH} | High-level Input Voltage | 2.0 | V _{CC} | V |
| V _{IL} | Low-level Input Voltage | 0 | 0.8 | V |
| V _{OH} | High-level Output Voltage (I _{OH} = -2.5mA) | 2.4 | | V |
| V _{OL} | Low-level Output Voltage (I _{OL} = +3.0mA) | | 0.4 | V |
| V _{OH} | V _{OH} High-level Output Voltage (I _{OH} = -2.0mA) | | | V |
| V _{OL} | V _{OL} Low-level Output Voltage (I _{OL} = +3.0mA) | | 0.4 | V |
| I _{CCA} | I _{CCA} Supply Current, Active Mode (3.6V 33MHz) | | 40 | mA |
| IL | Input or Output Leakage Current (V _{IN} = V _{CC} or GND) | | 10 | μA |
| I _{CCS} | Supply Current, Standby Mode | | 2 | mA |



9.4 AC Characteristics

Table 9-3. AC Characteristics

| Symbol | Description | Min | Тур | Max | Units |
|---------------------------------|--|-----|-----|-----|-------|
| T _{OE} ⁽¹⁾ | OE to Data Delay | | | 55 | ns |
| T _{CE} ⁽¹⁾ | CE to Data Delay | | | 60 | ns |
| T _{CAC} ⁽¹⁾ | CLK to Data Delay | | | 30 | ns |
| T _{OH} | Data Hold from CE, OE, or CLK | 0 | | | ns |
| T _{DF} ⁽²⁾ | CE or OE to Data Float Delay | | | 15 | ns |
| T _{LC} | CLK Low Time | 15 | | | ns |
| T _{HC} | CLK High Time | 15 | | | ns |
| T _{SCE} | CE Setup Time to CLK (to guarantee proper counting) | 25 | | | ns |
| T _{HCE} | CE Hold Time from CLK (to guarantee proper counting) | 0 | | | ns |
| T _{HOE} | RESET/OE Low Time (guarantees counter is reset) | 20 | | | ns |
| F _{MAX} | Maximum Input Clock Frequency SEREN = 0 | | | 10 | MHz |
| F _{MAX} | F _{MAX} Maximum Input Clock Frequency SEREN = 1 | | | 33 | MHz |
| T _{WR} | T _{WR} Write Cycle Time ⁽³⁾ | | 12 | | μs |
| T _{EC} | Erase Cycle Time ⁽³⁾ | | 33 | | S |

Notes: 1. AC test lead = 50pF.

- 2. Float delays are measured with 5pF AC loads. Transition is measured ±200mV from steady-state active levels.
- 3. See the AT17F(A) Programming Specification for procedural information.

Table 9-4. AC Characteristics When Cascading

| Symbol | Description | Min | Max | Units |
|---------------------------------|-------------------------------|-----|-----|-------|
| T _{CDF} ⁽²⁾ | CLK to Data Float Delay | | 50 | ns |
| T _{OCK} ⁽¹⁾ | CLK to CEO Delay | | 55 | ns |
| T _{OCE} ⁽¹⁾ | CE to CEO Delay | | 40 | ns |
| T _{OOE} ⁽¹⁾ | RESET/OE to CEO Delay | | 35 | ns |
| F _{MAX} | Maximum Input Clock Frequency | | 33 | MHz |

Notes: 1. AC test load = 50pF.

 Float delays are measured with 5pF AC loads. Transition is measured ± 200mV from steady-state active levels.

Figure 9-1. AC Waveforms

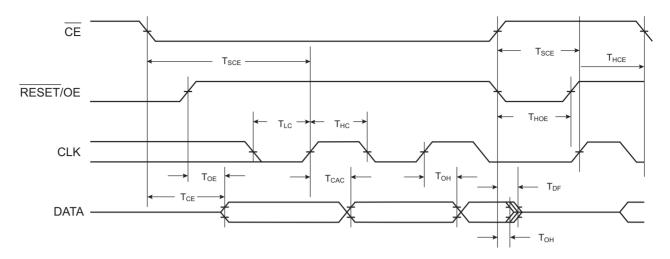
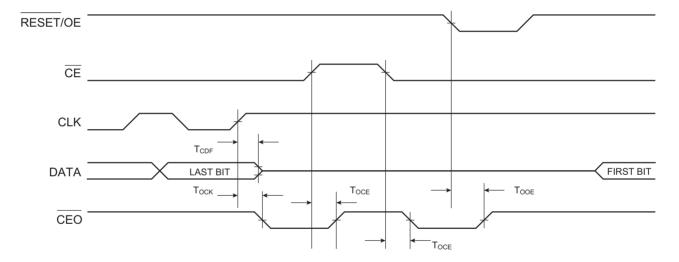


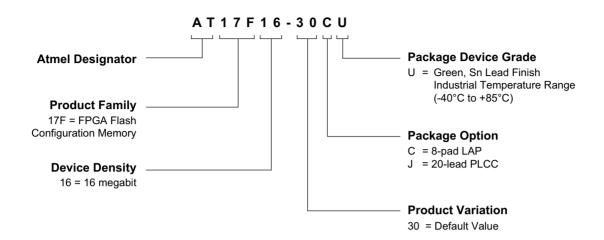
Figure 9-2. AC Waveforms when Cascading





10. Ordering Information

10.1 Ordering Code Detail



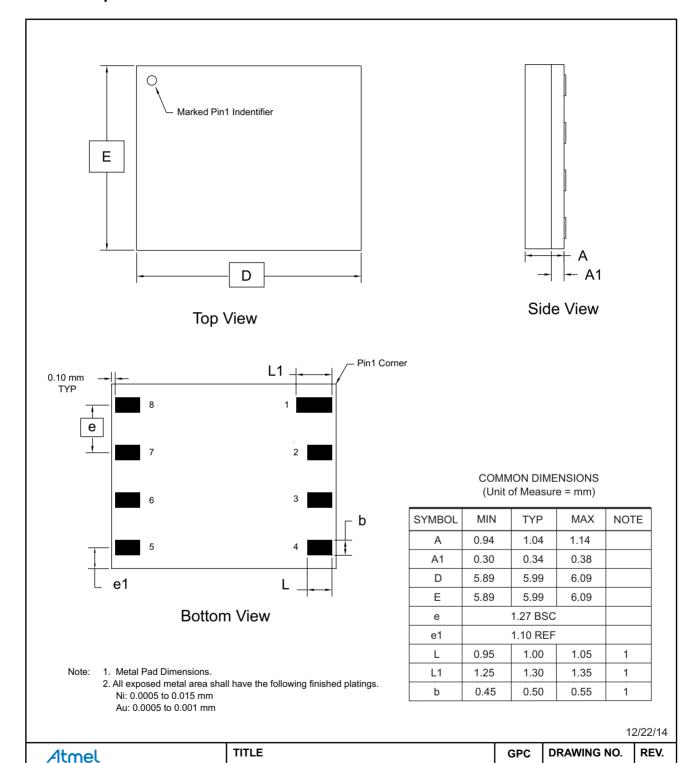
10.2 Ordering Codes

| | Memory Size | Atmel Ordering Code | Lead Finish | Package | Voltage | Operation Range |
|--|-------------|---------------------|--------------------------------|---------|---------|-----------------|
| | 16-Mbit | AT17F16-30CU | Sn (Lead-free/Halogen-free) | 8CN4 | 3.3V | Industrial |
| | | AT17F16-30JU | | 20J | 3.3V | (-40°C to 85°C) |

| Package Type | | | |
|--------------|---|--|--|
| 8CN4 | 8-pad, 6.00mm x 6.00mm x 1.04mm, Leadless Array Package (LAP) Pin-compatible with 8-lead SOIC/VOIC Packages | | |
| 20J | 20-lead, Plastic J-leaded Chip Carrier (PLCC) | | |

11. Packaging Information

11.1 8CN4 — 8-pad LAP



8CN4, 8-pad 6x6x1.04mm Body, 1.27mm pitch

Leadless Array Package (LAP)



Package Drawing Contact:

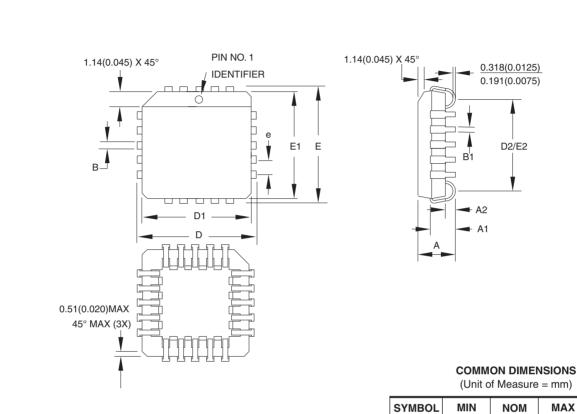
packagedrawings@atmel.com

8CN4

Ε

DMH

11.2 20J — 20-lead PLCC



- Notes: 1. This package conforms to JEDEC reference MS-018, Variation AA
 - 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
 - 3. Lead coplanarity is 0.004" (0.102mm) maximum

| (Offic of Micasaro = Illill) | | | | | | |
|------------------------------|-----------|-----|--------|--------|--|--|
| SYMBOL | MIN | NOM | MAX | NOTE | | |
| Α | 4.191 | _ | 4.572 | | | |
| A1 | 2.286 | _ | 3.048 | | | |
| A2 | 0.508 | _ | _ | | | |
| D | 9.779 | _ | 10.033 | | | |
| D1 | 8.890 | _ | 9.042 | Note 2 | | |
| Е | 9.779 | _ | 10.033 | | | |
| E1 | 8.890 | _ | 9.042 | Note 2 | | |
| D2/E2 | 7.366 | _ | 8.382 | | | |
| В | 0.660 | _ | 0.813 | | | |
| B1 | 0.330 | _ | 0.533 | | | |
| е | 1.270 TYP | | | | | |

10/04/01

Atmel

Package Drawing Contact: packagedrawings@atmel.com TITLE 20J, 20-lead, Plastic J-leaded Chip Carrier (PLCC) DRAWING NO. REV. 20J В

12. Revision History

| Doc Rev | Date | Comments |
|---------|---------|---|
| 3392G | 01/2015 | Removed commercial and 32-lead TQFP package options. Updated the 8CN4 package outline drawing, template, Atmel logos, and disclaimer page. Added an ordering code detail. |
| 3392F | 02/2008 | Removed -30JC, -30JI, -30BJC and -30BJI devices from ordering information. |
| 3392E | 08/2007 | Removed -30CC and -30Cl devices from ordering information. Announced last-time buy for -30JC, -30BJC, -30JI, and -30BJI devices. |
| 3392D | 03/2006 | Added last-time buy for AT17F16-30CC and AT17F16-30Cl. |













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